

SLE 77CLF601P(M)

Short Product Overview

Features

- 60 kByte SOLID FLASH™
- 4 kByte RAM
- 27pF chip capacity

Applications

SLE 77CLF is the ideal platform for multi-application solutions:

- Transport Ticketing
- Access Control
- Micropayment
- Basic ID application


Description

Bundling Infineon's long-standing experience in contactless applications, the SLE 77CLF601P (M) is the ideal platform when outstanding contactless performance is required. Highlights include

- NVM in SOLID FLASH™ for record time-to-market
- Common Criteria EAL 5+

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Description



Product name	SLE 77CLF601P(M)  Solid Flash™
Product description	Dual-interface and Contactless Security Cryptocontroller
Interfaces	ISO 7816, ISO 14443 A/B, ISO 18092 passive mode, optional NRG™ interface
Memory	60 kByte SOLID FLASH™ 4 kByte RAM
CPU	16-bit
Symmetrical cryptography	DES, 3DES, AES up to 256-bit
Asymmetrical cryptography	RSA up to 4096-bit, ECC up to 521-bit
RNG	Hybrid Random number generator (HRNG, consisting of TRNG/PRNG) – according to BSI AIS20/31
Ambient temperature	-25 to + 85 °C
Data retention	Typical data retention of minimum 10 years @ 25 °C
Delivery forms	Dual interface module, Contactless module, Wafer sawn
Typical applications	Transport Ticketing, Access Control, Micropayment Basic, ID application
Certification level	CC EAL5+ high

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